

FLEX AND CHIP ON FLEX

FLEX-HDI • BUMPLETS • MILITARY

What others can do only on rigid boards, Compunetics is able to achieve on flex. Compunetics maintains its place at the highest level of design expertise and manufacturing skill.

compunetics
excellence, measured in microns.

Compunetics' track record of excellence in flex and chip on flex products is unparalleled in the industry.

Our quality has earned us the role as a major presence in the commercial and military flex market, a regular choice for new material beta testing, and the company of choice when customers require the development of new products.

Compunetics' flex boards are used for a variety of applications including:

- Military
- Medical
- Aerospace
- Chip testing
- High energy physics

Compunetics' design and manufacturing teams are all under one roof for constant collaboration.

Our flex features include:

- Single/Double/Multilayers
- Variety of Upilex and DuPont adhesiveless materials
- Beta site for "all-polyimide" bondply product
- Wedge/ball bonding gold surface
- 2 mil (50 μ m) trace/space
- Ohmega resistors on flex
- Small-to-medium volume
- Quick turn capability

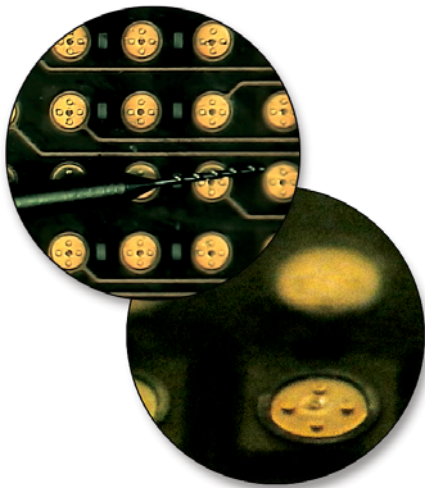
FLEX BOARD

Compunetics is the only manufacturer to make flex with 4 steps of selective plating.

This process creates bumpets that enable mechanical connection with an absolute minimum of force.

Specifications:

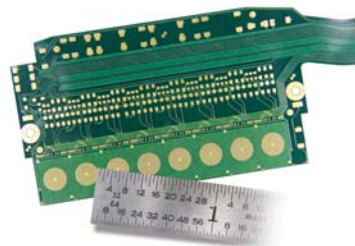
Layers: 3
4 Steps Of Selective Plating
Material: Pyralux
Selective Plating
Trace/Space: 3/3 (75/75 μ m)
Finish: Electrolytic Ni/Hard Au



CHIP ON FLEX BOARD

High-Energy Particle Detector:

Layers: 2
Trace/Space: 2/2 (50/50 μ m)
Microvias: 2 mils
Finish: Immersion Au over Ni
Selective Plating
Material: 2 mil Adhesiveless Pyralux



MILITARY FLEX BOARD

Military:

Layers: 8
Trace/Space: 3.5 (87 μ m)
Finish: HASL
Differential Controlled Impedance

